

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1682	361/783	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/15 22:19
L3	731	349/150	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/15 22:45
L4	2215	349/58	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/15 23:15
S1	4	"4,903,114".pn. or "5,571,027".pn. or "5,847,572".pn. or "6,373,128".pn.	USPAT	OR	OFF	2008/08/04 14:13
S2	1	"7345326".pn.	USPAT	OR	OFF	2008/08/08 10:38
S3	3506	(base near plate) with (project\$3 or protrud \$3 or support\$3) and (project\$3 or protrud \$3 or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate) with (base near plate)	USPAT	OR	ON	2008/08/08 11:51
S4	1364	(base near plate) with (project\$3 or protrud \$3 or support\$3) and (project\$3 or protrud \$3 or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate) with (over or mount\$3) with (base near plate)	USPAT	OR	ON	2008/08/08 11:52

S5	1364	(base near plate) with (project\$3 or protrud \$3 or support\$3) and (project\$3 or protrud \$3 or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate) with (over or mount\$3 or "On") with (base near plate)	USPAT	OR	ON	2008/08/08 11:53
S6	1364	(base near plate) with (project\$3 or protrud \$3 or support\$3) and (project\$3 or protrud \$3 or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate) with (over or mount\$3 or "on") with (base near plate)	USPAT	OR	ON	2008/08/08 11:53
S7	284	S6 and (semicondcutor or die or chip or IC or dice)	USPAT	OR	ON	2008/08/08 11:59
S8	344	S6 and (semiconductor or die or chip or IC or dice)	USPAT	OR	ON	2008/08/08 11:59
S9	1	"20070158840"	US-PGPUB; USPAT	OR	ON	2008/08/08 12:58
S10	3091	(base near plate) with (project\$3 or protrud \$3 or support\$3) and (project\$3 or protrud \$3 or support\$3) with (over or mount\$3 or "on") with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 12:59

S11	7953	(base near plate) with (project\$3 or protrud \$3 or support\$3) and (project\$3 or protrud \$3 or support\$3) with (over or mount\$3 or "on" or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 12:59
S12	2133	S11 and (semiconductor or die or chip or IC or dice)	USPAT	OR	ON	2008/08/08 13:00
S13	1823	S12 not S8	USPAT	OR	ON	2008/08/08 13:00
S14	133	("3437929" "3810016" "4312117" "4506938" "4585991" "4636722" "4758785" "4922192" "4924589" "4937653" "4952272" "4963225" "5006792" "5055778" "5066907" "5072116" "5073117" "5088190" "5103557" "5123850" "5148103" "5177438" "5177439" "5262718" "5304922" "5323035" "5326428").FN. OR ("5495179").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 13:56

S15	28	("4234666" "4390598" "4459607" "4571354" "4684884" "4701781" "4706811" "4951120").PN. OR ("5061988").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 14:03
S16	64	("4042861" "4216577" "4222516" "4501960" "4509098" "4532419" "4539472").PN. OR ("4725924").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 14:15
S17	45	("3404215" "3480836" "3544857" "3549782" "3670639" "3702953" "3718842" "3778999" "3873889").PN. OR ("4042861").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 14:26
S18	51	("4571542" "4585991" "4597617" "4899107" "4916002" "4937653" "4952272" "4963225" "5006792" "5072116" "5073117" "5088190" "5103557" "5107206" "5123850" "5137461" "5177438" "5177439" "5177528" "5206585" "5219765" "5239260" "5249450" "5262718" "5302891" "5323035" "5326428"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 14:33

		"5367253" "5402077" "5419807" "5420520" "5424652" "5440240" "5483174" "5483741" "5487999" "5495179" "5519332" "5539324" "5541525" "5578526" "5578934" "5585282" "5781022" "6091250" "6091251").PN. OR ("6828812").URPN.				
S19	1290	257/727	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/08 14:57
S20	5281	257/737	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/08 14:58
S21	1626	361/783	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/08 15:14
S22	668	349/150	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/08 15:50
S23	1924	349/58	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/08 16:09

S24	9838	(base near plate) same (support\$3 or layer) and (support\$3 or layer) with (over or mount\$3 or "on" or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 16:12
S25	3266	(base near plate) same (support\$3) with (over or mount\$3 or "on" or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 16:12
S26	9	(base near plate) same (support\$3 near layer) with (over or mount\$3 or "on" or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 16:13
S27	245	(base near plate) same (ring) with (over or mount\$3 or "on" or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 16:13
S28	14	(base near plate) same support\$3 near (ring) with (over or mount\$3 or "on" or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 16:20
S29	245	(base near plate) same (ring) with (over or mount\$3 or "on" or support\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate)	USPAT	OR	ON	2008/08/08 16:20

S30	485	(base near plate) with (project\$3 or protrud\$3) and (project\$3 or protrud\$3) with (lead or contact or pad or terminal or wir\$3) and (hous\$3 or carrier or module or substrate) with (over or mount\$3 or "on") with (base near plate)	USPAT	OR	ON	2008/08/08 16:21
S31	33	("4628407" "4774127" "4811165" "4858071" "4922324" "5101322" "5103375" "5159751" "5170326" "5266746" "5276418" "5310966" "5402313" "5523919" "5615087" "5616888").PN. OR ("5812375").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 16:25
S32	21	("4142161" "4345118" "4349881" "4415827" "4421621" "4633124" "5157472" "5269185" "5302880" "5325574").PN. OR ("5531091").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 16:27
S33	2853	361/707	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/08 16:31
S34	8	("4233645" "5459352" "5623394" "5812375" "6151215" "6365964").PN. OR ("7023699").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 16:35

S35	35	("4466483" "4682270" "5218215" "5302467" "5708566" "5812375").PN. OR ("6058013").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 16:37
S36	17	("3757271" "5198964" "5450288" "5497031" "5661902" "5708566" "5789805" "5812375" "5841340" "5869897" "5877555").PN. OR ("5933327").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 16:40
S37	28	("4234666" "4390598" "4459607" "4571354" "4684884" "4701781" "4706811" "4951120").PN. OR ("5061988").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/08 16:49
S38	18	257/E23.105	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/08 17:14
S39	1	"20070158840"	US-PGPUB; USPAT	OR	OFF	2009/03/11 16:06
S40	110319	(semiconductor or die or dice or chip or IC) and hous\$3 and (support\$3 or spacer)	USPAT	OR	ON	2009/03/11 21:43
S41	32456	(semiconductor or die or dice or chip or IC) and hous\$3 with (support\$3 or spacer)	USPAT	OR	ON	2009/03/11 21:43
S42	8540	(semiconductor or die or dice or chip or IC) and hous\$3 with (support\$3 or spacer) with (base or plat\$3 or carrier)	USPAT	OR	ON	2009/03/11 21:44

S43	4608	(semiconductor or die or dice or chip or IC) and hous\$3 with (support\$3 or spacer) with (base or plat\$3 or carrier) and (lead or terminal)	USPAT	OR	ON	2009/03/11 21:44
S44	1547	(semiconductor or die or dice or chip or IC) and hous\$3 with (support\$3 or spacer) with (base or plat\$3 or carrier) and (lead or terminal) with hous\$3	USPAT	OR	ON	2009/03/11 21:45
S45	66	("4042861" "4216577" "4222516" "4501960" "4509098" "4532419" "4539472").PN. OR ("4725924").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/03/13 15:21
S46	53	("3271627" "3487267" "3789248" "3984166" "4351580" "4390220" "4458968" "4546407" "4591896" "4624303" "4747017").PN. OR ("4885126").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/03/13 18:07
S47	1643	(semiconductor or die or dice or chip or IC) and hous\$3 with (frame or protrud\$3 or project\$3) with (base or plat\$3 or carrier) and (lead or terminal or pad or finger) with (frame or protrud\$3 or project\$3)	USPAT	OR	ON	2009/03/13 18:23

S48	365	(semiconductor or die or dice or chip or IC) and hous\$3 with (frame or protrud\$3 or project\$3) with (base or plat\$3 or carrier) and (lead or terminal or pad or finger) with (frame or protrud\$3 or project\$3) and (frame or protrud\$3 or project\$3) with (bigger or tall or larger or large or big or higher)	USPAT	OR	ON	2009/03/13 18:24
S49	235	(semiconductor or die or dice or chip or IC) and (hous\$3 or packag\$3) with (frame or protrud\$3 or project\$3) with (module) and (lead or terminal or pad or finger) with (frame or protrud\$3 or project\$3) and (frame or protrud\$3 or project\$3) with (bigger or tall or larger or large or big or higher)	USPAT	OR	ON	2009/03/13 18:37
S50	21	257/E23.105	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/13 18:43
S51	1329	257/727	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/13 18:43
S52	5636	257/737	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/13 18:50
S53	2970	361/707	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/13 18:57

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